

# SN54BCT760, SN74BCT760 OCTAL BUFFERS/DRIVERS WITH OPEN-COLLECTOR OUTPUTS

SCBS034B – JULY 1989 – REVISED NOVEMBER 1993

- Open-Collector Version of 'BCT244
- Open-Collector Outputs Drive Bus Lines or Buffer Memory Address Registers
- ESD Protection Exceeds 2000 V Per MIL-STD-883C Method 3015
- Packages Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Standard Plastic and Ceramic 300-mil DIPs (J, N)

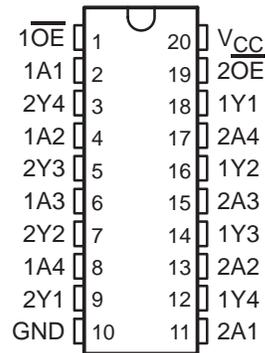
## description

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

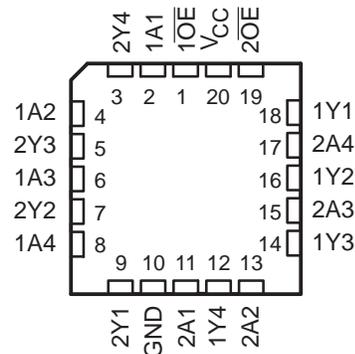
The 'BCT760 is organized as two 4-bit buffers/line drivers with separate output-enable ( $\overline{OE}$ ) inputs. When  $\overline{OE}$  is low, the device passes data from the A inputs to the Y outputs. When  $\overline{OE}$  is high, the outputs are in the high-impedance state.

The SN54BCT760 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74BCT760 is characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

SN54BCT760 . . . J OR W PACKAGE  
SN74BCT760 . . . DW OR N PACKAGE  
(TOP VIEW)



SN54BCT760 . . . FK PACKAGE  
(TOP VIEW)



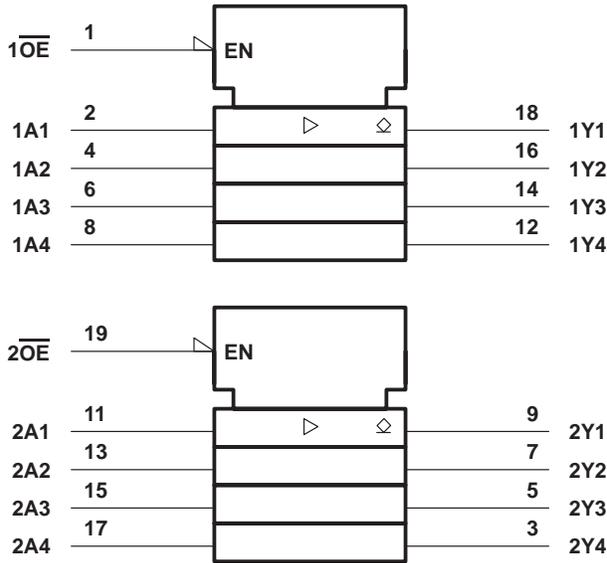
FUNCTION TABLE  
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	H

# SN54BCT760, SN74BCT760 OCTAL BUFFERS/DRIVERS WITH OPEN-COLLECTOR OUTPUTS

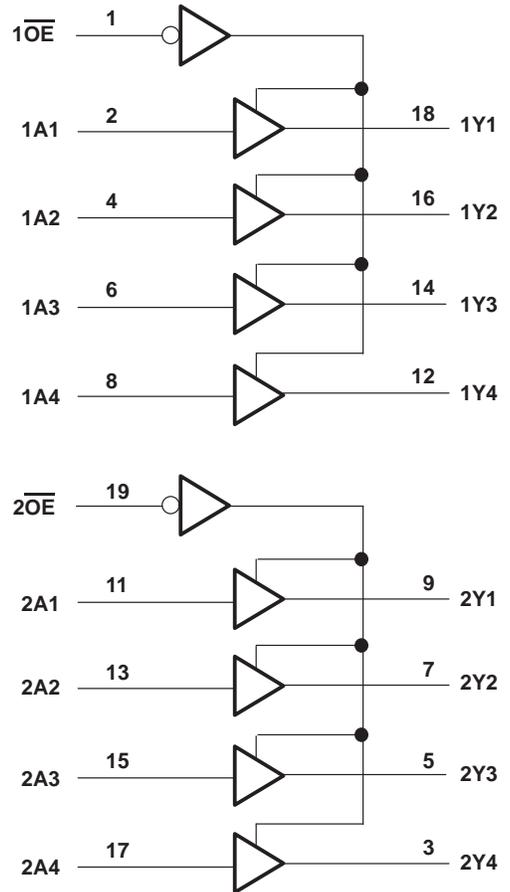
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## logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, $V_{CC}$ .....	- 0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	- 0.5 V to 7 V
Input current range, $I_I$ .....	- 30 mA to 5 mA
Voltage range applied to any output in the disabled or power-off state, $V_O$ .....	- 0.5 V to 5.5 V
Voltage range applied to any output in the high state, $V_{OH}$ .....	- 0.5 V to $V_{CC}$
Current into any output in the low state: SN54BCT760 .....	96 mA
SN74BCT760 .....	128 mA
Operating free-air temperature range: SN54BCT760 .....	- 55°C to 125°C
SN74BCT760 .....	0°C to 70°C
Storage temperature range .....	- 65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The negative input voltage rating may be exceeded if the input clamp current rating is observed.

**SN54BCT760, SN74BCT760**  
**OCTAL BUFFERS/DRIVERS**  
**WITH OPEN-COLLECTOR OUTPUTS**  
 SCBS034B – JULY 1989 – REVISED NOVEMBER 1993

**recommended operating conditions**

		SN54BCT760			SN74BCT760			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage			0.8			0.8	V
V <sub>OH</sub>	High-level output voltage			5.5			5.5	V
I <sub>IK</sub>	Input clamp current			-18			-18	mA
I <sub>OL</sub>	Low-level output current			48			64	mA
T <sub>A</sub>	Operating free-air temperature	-55		125	0		70	°C

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		SN54BCT760			SN74BCT760			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2			-1.2	V
V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA	0.38	0.55					V
		I <sub>OL</sub> = 64 mA				0.42	0.55		
I <sub>I</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V			0.1			0.1	mA
I <sub>IH</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20			20	μA
I <sub>IL</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.5 V			-1			-1	mA
I <sub>OH</sub>	V <sub>CC</sub> = 4.5 V,	V <sub>OH</sub> = 5.5 V			0.1			0.1	mA
I <sub>CC</sub>	V <sub>CC</sub> = 5.5 V,	Outputs high	21	33		21	33		mA
		Outputs low	48	76		48	76		
		$\overline{\text{OE}}$ disabled	6	10		6	10		
C <sub>i</sub>	V <sub>CC</sub> = 5 V,	V <sub>I</sub> = 2.5 V or 0.5 V		6			6		pF
C <sub>o</sub>	V <sub>CC</sub> = 5 V,	V <sub>I</sub> = 2.5 V or 0.5 V		10			10		pF

† All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

**switching characteristics (see Note 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500 Ω, T <sub>A</sub> = 25°C			V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX‡				UNIT
			'BCT760			SN54BCT760		SN74BCT760		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	Any A	Y	6.3	8	9.5	6.3	11.1	6.3	10	ns
t <sub>PHL</sub>			2.1	4.3	6.5	2.1	7.7	2.1	7.2	
t <sub>PLH</sub>	$\overline{\text{OE}}$	Y	8.6	13	15.2	8.6	18.7	8.6	17.5	ns
t <sub>PHL</sub>			3.2	6.2	8.9	3.2	10.4	3.2	9.9	

‡ For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.





**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">5962-9093801M2A</a>	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9093801M2A SNJ54BCT 760FK
<a href="#">5962-9093801MRA</a>	Active	Production	CDIP (J)   20	20   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9093801MR A SNJ54BCT760J
<a href="#">5962-9093801MSA</a>	Active	Production	CFP (W)   20	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9093801MS A SNJ54BCT760W
<a href="#">SN54BCT760J</a>	Active	Production	CDIP (J)   20	20   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54BCT760J
SN54BCT760J.A	Active	Production	CDIP (J)   20	20   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54BCT760J
<a href="#">SN74BCT760DW</a>	Obsolete	Production	SOIC (DW)   20	-	-	Call TI	Call TI	0 to 70	BCT760
SN74BCT760DW.B	Obsolete	Production	SOIC (DW)   20	-	-	Call TI	Call TI	0 to 70	BCT760
<a href="#">SN74BCT760DWR</a>	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT760
SN74BCT760DWR.A	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT760
SN74BCT760DWR.B	Active	Production	SOIC (DW)   20	2000   LARGE T&R	-	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT760
<a href="#">SN74BCT760N</a>	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74BCT760N
SN74BCT760N.A	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74BCT760N
<a href="#">SNJ54BCT760FK</a>	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9093801M2A SNJ54BCT 760FK
SNJ54BCT760FK.A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9093801M2A SNJ54BCT 760FK
<a href="#">SNJ54BCT760J</a>	Active	Production	CDIP (J)   20	20   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9093801MR A SNJ54BCT760J
SNJ54BCT760J.A	Active	Production	CDIP (J)   20	20   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9093801MR A SNJ54BCT760J

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">SNJ54BCT760W</a>	Active	Production	CFP (W)   20	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9093801MS A SNJ54BCT760W
SNJ54BCT760W.A	Active	Production	CFP (W)   20	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9093801MS A SNJ54BCT760W

**(1) Status:** For more details on status, see our [product life cycle](#).

**(2) Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

**(3) RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

**(4) Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**(5) MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

**(6) Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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**OTHER QUALIFIED VERSIONS OF SN54BCT760, SN74BCT760 :**

- Catalog : [SN74BCT760](#)
- Enhanced Product : [SN74BCT760-EP](#), [SN74BCT760-EP](#)
- Military : [SN54BCT760](#)

## NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**

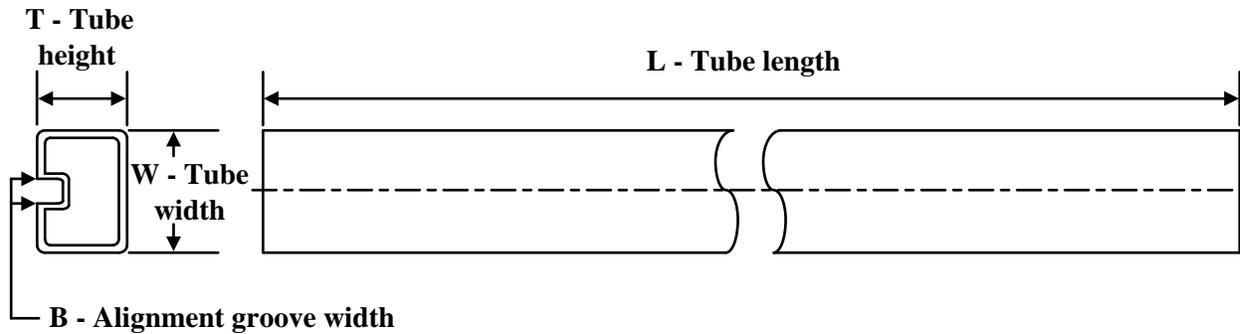

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74BCT760DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74BCT760DWR	SOIC	DW	20	2000	356.0	356.0	45.0

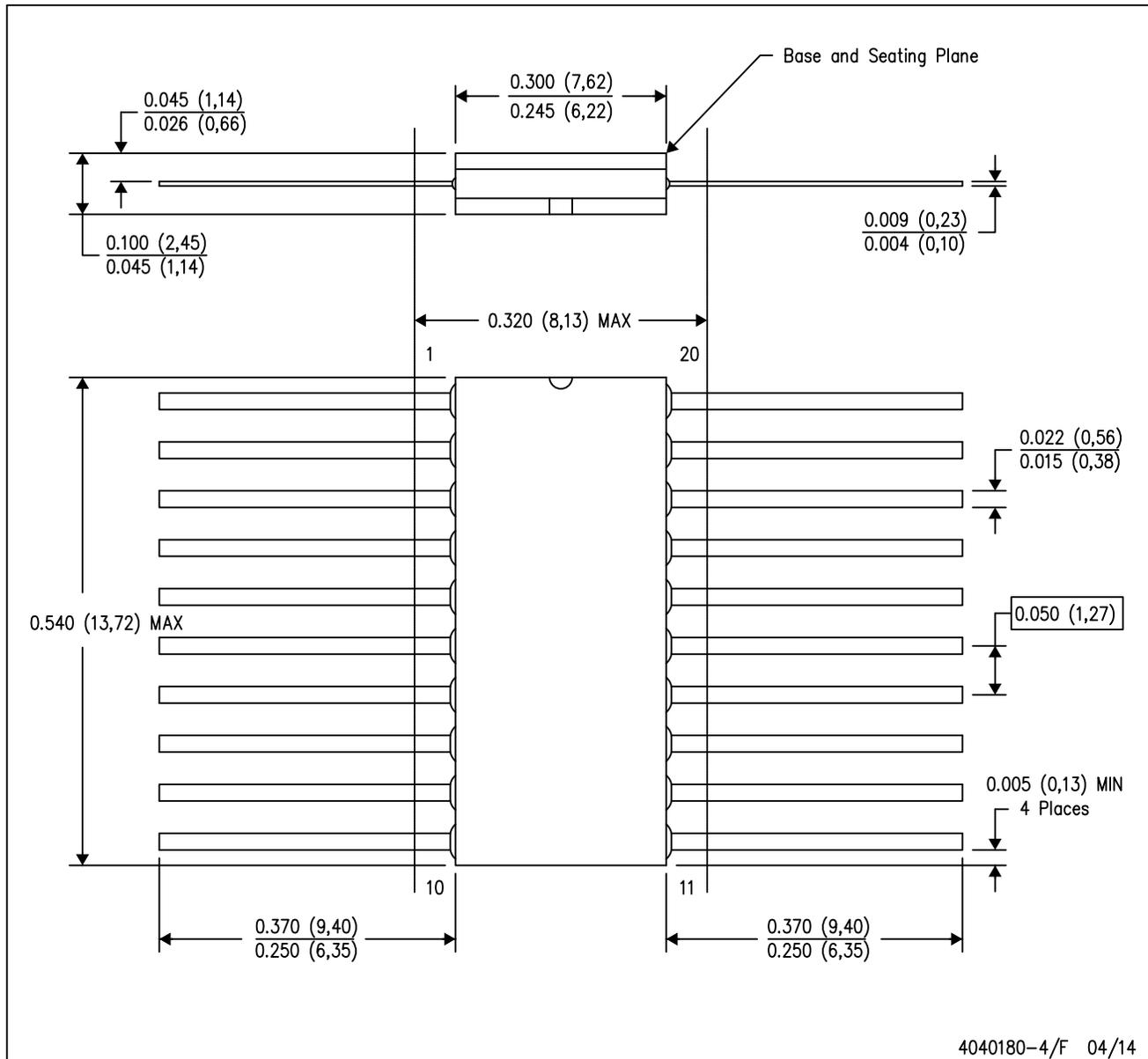
**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9093801M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9093801MSA	W	CFP	20	25	506.98	26.16	6220	NA
SN74BCT760N	N	PDIP	20	20	506	13.97	11230	4.32
SN74BCT760N.A	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54BCT760FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54BCT760FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54BCT760W	W	CFP	20	25	506.98	26.16	6220	NA
SNJ54BCT760W.A	W	CFP	20	25	506.98	26.16	6220	NA

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## GENERIC PACKAGE VIEW

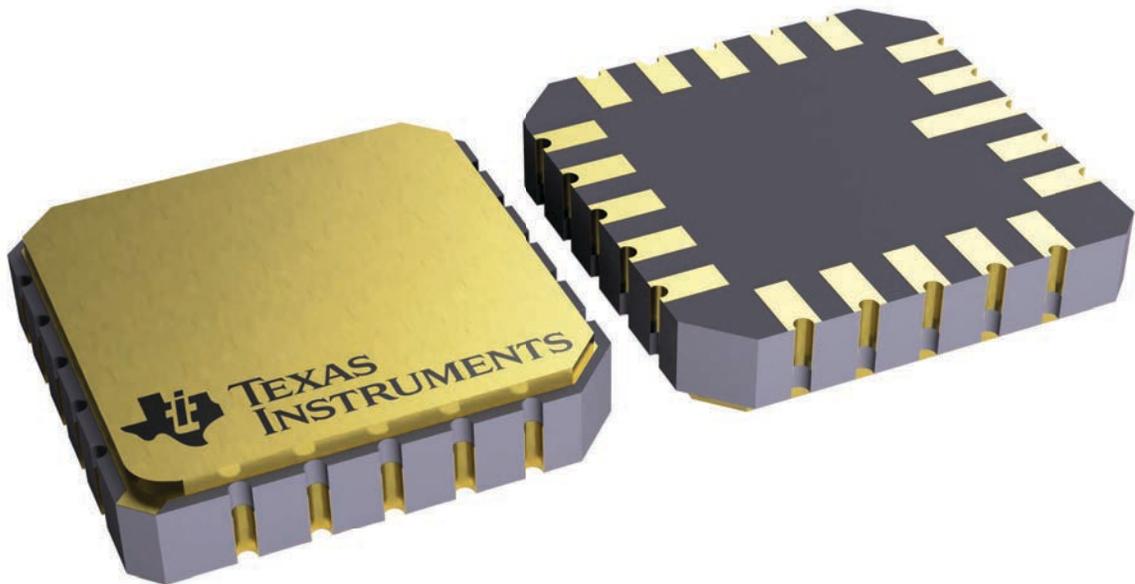
**FK 20**

**LCCC - 2.03 mm max height**

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4229370VA\

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

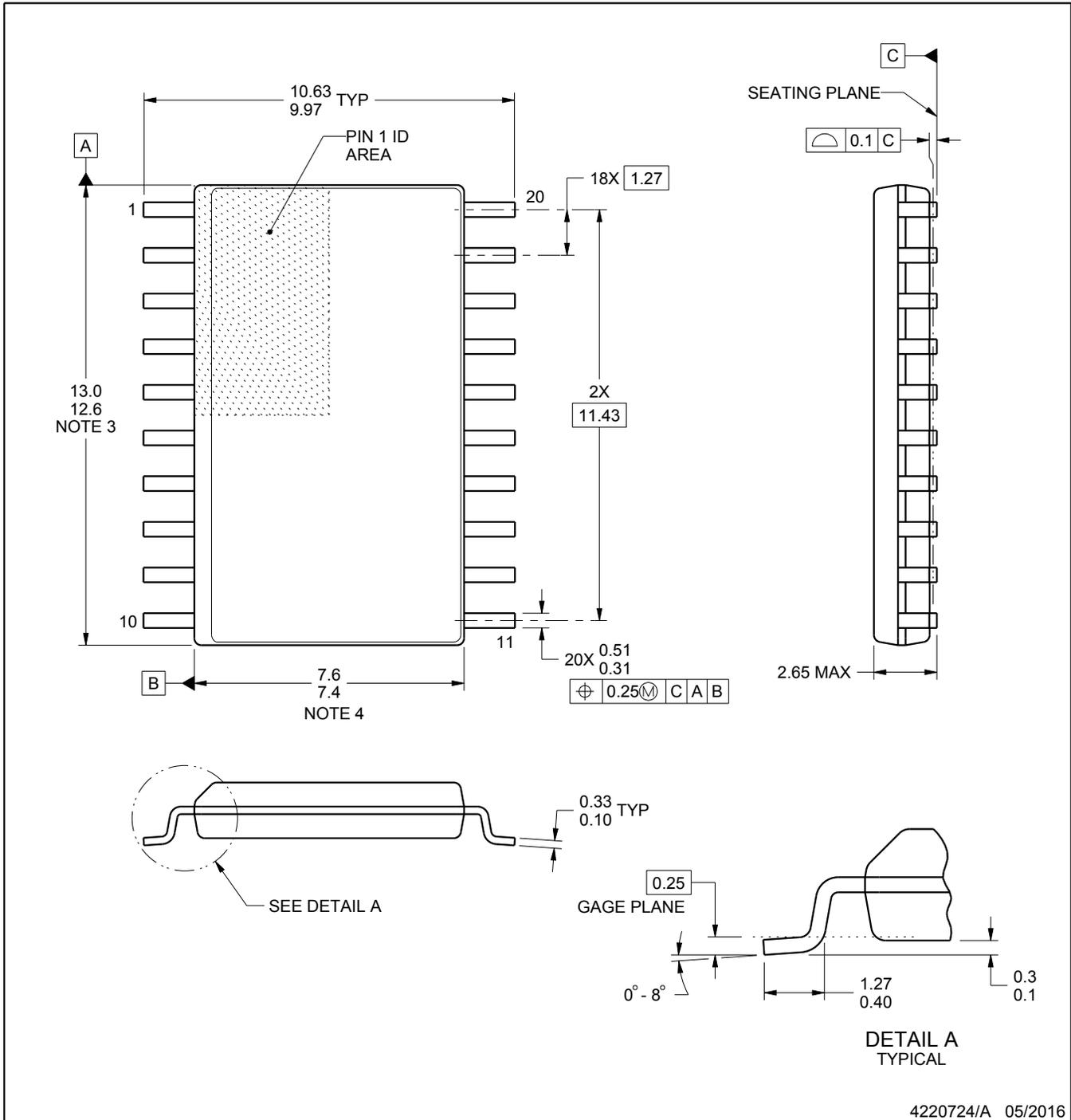
# DW0020A



# PACKAGE OUTLINE

## SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

### NOTES:

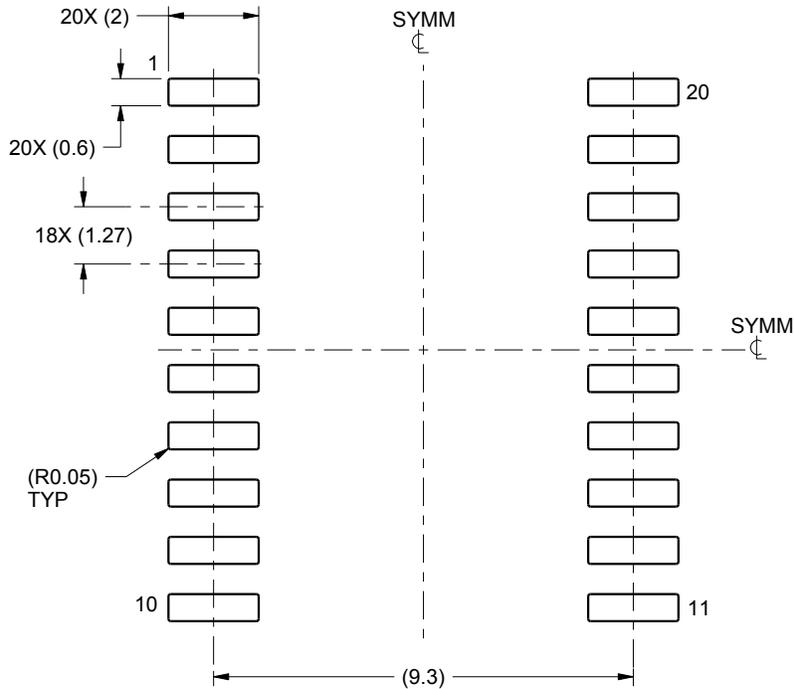
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

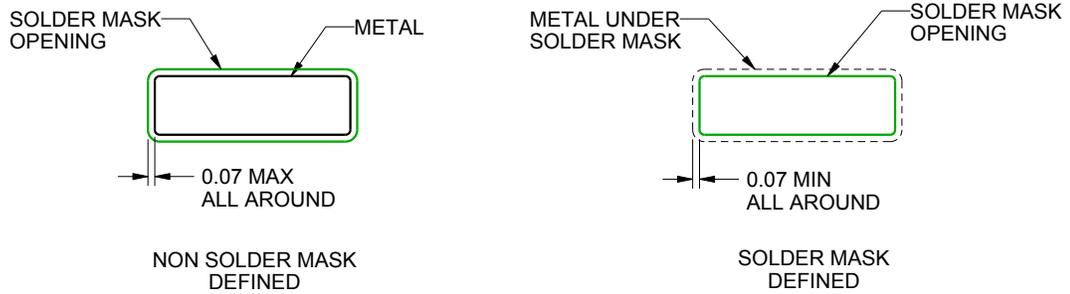
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

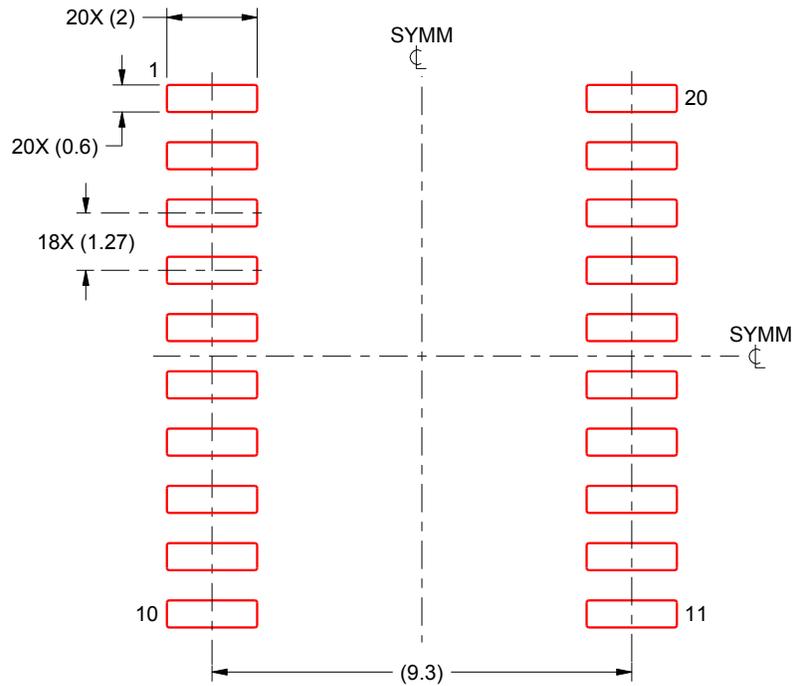
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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